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(54) **ELECTRICALLY FUNCTIONAL CIRCUIT BOARD CORE MATERIAL**

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(57) **ABSTRACT**

An improved circuit board core material, and method of making the circuit board core material, is provided wherein the circuit board core material is particularly suitable for use in a circuit board. The circuit board core material comprises a laminate. The laminate comprises a prepreg layer with a first clad layer on the prepreg layer wherein the prepreg layer comprises a pocket. An electronic component is in the pocket wherein the electronic component comprises a first external termination and a second external termination. The first external termination is laminated to, and in electrical contact with, the first clad layer and said second external termination is in electrical contact with a conductor.

